PCN Number:	20150821000A	**PCN Date:**	01/27/2016
Title:	Qualification of ASESH as Additional Assembly Site for Select TSSOP Package Devices		
Customer Contact:	PCN Manager	**Dept:**	Quality Services
Proposed 1st Ship Date:	11/24/2015	**Estimated Sample Availability:**	Date Provided at Sample request

Change Type:					
☒	Assembly Site	☐	Assembly Process	☒	Assembly Materials
☐	Design	☐	Electrical Specification	☐	Mechanical Specification
☒	Test Site	☐	Packing/Shipping/Labeling	☐	Test Process
☐	Wafer Bump Site	☐	Wafer Bump Material	☐	Wafer Bump Process
☐	Wafer Fab Site	☐	Wafer Fab Materials	☐	Wafer Fab Process

PCN Details

Description of Change:

Revision A is to update the description of change to provide correction on the material differences table and remove select devices in the Product Affected Section (with ~~strikethrough~~) and highlighted in yellow. These devices were inadvertently added and not affected by this change. We apologize for any inconvenience this may have caused.

Qualification of ASESH as Additional Assembly Site for Select TSSOP Package Devices. Assembly differences are shown in the following table:

Assembly Site	Assembly Site Origin	Assembly Country Code	Assembly Site City
TI Malaysia	MLA	MY	Kuala Lumpur
ASESH	**ASH**	**CN**	**Shanghai**

Material Differences:

	TI Malaysia	ASESH
Mount Compound	4042500	EY1000063
Mold Compound	4206193	EN2000507
Lead Finish	NiPdAu	Matte Sn

Upon expiration of this PCN, TI will combine lead free solutions in a single ***standard part number***, for example; ***CDCV304PW***– can ship with both Matte Sn and NiPdAu. When available customers may specify NiPdAu finish by ordering the part with the G4 suffix, e.g. ***CDCV304PWG4.***″

Reason for Change:

Continuity of Supply

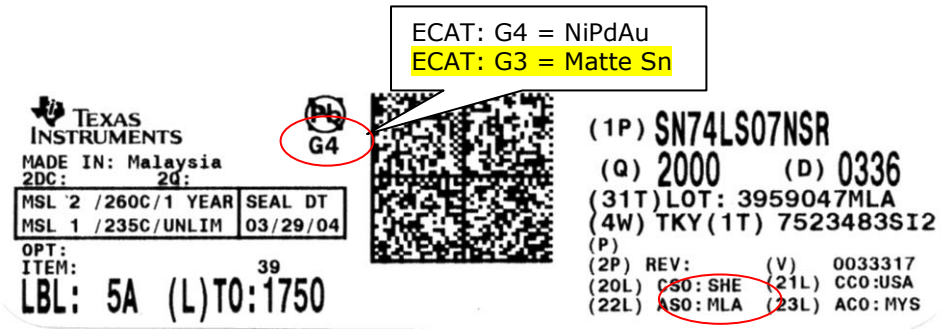
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

Assembly Site			
TI Malaysia	Assembly Site Origin (22L)	ASO: MLA	ECAT: G4
ASESH	Assembly Site Origin (22L)	ASO: ASH	ECAT: G3

Sample product shipping label (not actual product label)



ASSEMBLY SITE CODES: TI Malaysia =K, ASESH = A

Product Affected:

CDCV304PW	~~CDCV304PWG4~~	CDCV304PWR	~~CDCV304PWRG4~~

Qualification Report

CDCV304PW: Qualification of alternative Assembly Site (ASESH)

Product Attributes

Attributes	Qual Device: CDCV304
Assembly Site	ASE SHANGHAI (ASESH)
Package Family	TSSOP
Flammability Rating	UL 94 V-0
Wafer Fab Site	ANAM (DONGBU)
Wafer Fab Process	33C10

- QBS: Qual By Similarity
- Qual Device CDCV304 is qualified at LEVEL1-260C

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: CDCV304
PC	PreCon Level 1	25C	1/280/0
AC	Autoclave 121C	96 Hours	1/80/0
TC	Temperature Cycle, -65/150C	500 Cycles	1/80/0
HTSL	High Temp Storage Bake 150C	1000 Hours	1/80/0
MQ	Manufacturability	(per mfg. Site specification)	Pass
ED	Electrical Characterization	Per Datasheet Parameters	1/Pass

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
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